TITLE OF THE INVENTION: BUMP FORMING METHOD, BUMP FORMING APPARATUS, AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD

ABSTRACT

A bump forming method includes: a bonding step of bonding the leading end of a wire extending out of the tip of a bonding tool to a first point X1; a wire pay-out step of moving the bonding tool in a direction away from the first point; a thin portion forming step of pressing a portion of the wire at a second point X2 on a reference plane using the bonding tool to form a thin portion (64) in the wire; a wire shaping step of shaping the wire bonded to the first point in a manner rising from the reference plane; and a bump forming step of cutting the wire at the thin portion to form a bump (60) having a shape rising from the reference plane at the first point. It is therefore possible to form a bump having a desired height more easily and efficiently.

FIGURE 2(A) – 2(C)